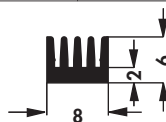
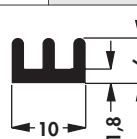


$B \triangleq$

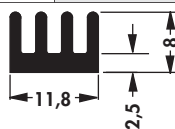
art. no.	↔ [mm]	R_{th} [K/W]	art. no.	↔ [mm]	R_{th} [K/W]
ICK SMD E 15 SA	15.3	27	ICK SMD E 29 SA	29.0	18
ICK SMD E 22 SA	22.3	21			



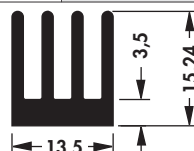
art. no.	↔ [mm]	R_{th} [K/W]	art. no.	↔ [mm]	R_{th} [K/W]
ICK SMD F 8 ...	8	74	ICK SMD F 19 ...	19	37
ICK SMD F 10 ...	10	71	ICK SMD F 21 ...	21	33
ICK SMD F 17 SA	17	42	ICK SMD F 26 ...	26	26



art. no.	↔ [mm]	R_{th} [K/W]	art. no.	↔ [mm]	R_{th} [K/W]
ICK SMD G 8 MI	8	73	ICK SMD G 17 SA	17	41
ICK SMD G 10 ...	10	70	ICK SMD G 19 SA	19	36
ICK SMD G 13 SA	13	61	ICK SMD G 21 ...	21	32



art. no.	↔ [mm]	R_{th} [K/W]	art. no.	↔ [mm]	R_{th} [K/W]
ICK SMD H 8 ...	8	33.0	ICK SMD H 19 SA	19	23.0
ICK SMD H 10 ...	10	29.0	ICK SMD H 25 ...	25	20.0
ICK SMD H 17 ...	17	24.5			



art. no.	↔ [mm]	R_{th} [K/W]	art. no.	↔ [mm]	R_{th} [K/W]
ICK SMD K 8 ...	8	25.6	ICK SMD K 17 ...	17	19.4
ICK SMD K 10 SA	10	23.4	ICK SMD K 19 ...	19	18.0
ICK SMD K 13 ...	13	21.5	ICK SMD K 21 ...	21	16.5



art. no.	↔ [mm]	R_{th} [K/W]	art. no.	↔ [mm]	R_{th} [K/W]
ICK SMD M 8 SA	8	72	ICK SMD M 19 SA	19	35
ICK SMD M 10 SA	10	66	ICK SMD M 21 SA	21	31
ICK SMD M 17 MI	17	40			

please indicate: ... surface
SA = black anodised
MI = solderable surface

Extruded heatsinks
 Pin heatsinks for IC
 Insulating clamping parts
 Thermal conductive glue

→ A 22 – 83
 → B 21 – 27
 → E 43
 → E 21 – 22

Thermally conductive foil
 Thermal conductive paste
 Hole pattern
 Technical introduction

→ E 5 – 13
 → E 19 – 20
 → A 21
 → A 2 – 7